

In re Application of Hiroyuki Arakawa  
Application No. Unassigned

*IN THE ABSTRACT*

*Replace the abstract with:*

*A7*  
ABSTRACT OF THE DISCLOSURE

A semiconductor device includes an inner lead, a first ball on the inner lead, a bonding pad on the semiconductor device, a second ball on the bonding pad, and a bonding wire connecting the first and second balls. The second ball is formed by mechanically deforming the bonding wire.

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